



#### 40V NPN SMALL SIGNAL TRANSISTOR IN X1-DFN1006-3

#### **Features**

- BV<sub>CEO</sub> > 40V
- I<sub>C</sub> = 200mA High Collector Current
- P<sub>D</sub> = 1000mW Power Dissipation
- 0.60mm<sup>2</sup> Package Footprint, 13 Times Smaller than SOT23
- 0.5mm Height Package Minimizing Off-Board Profile
- Complementary PNP Type MMBT3906LP
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q101, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotive-products/.

 This part is qualified to JEDEC standards (as references in AEC-Q101) for High Reliability.

https://www.diodes.com/quality/product-definitions/

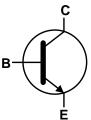
## **Mechanical Data**

- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
  Terminals: Finish NiPdAu, Solderable per MIL-STD-202,
  Method 208
- Weight: 0.0008 grams (Approximate)

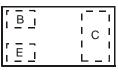
X1-DFN1006-3



**Bottom View** 



Device Symbol



Top View Device Schematic

# Ordering Information (Note 4)

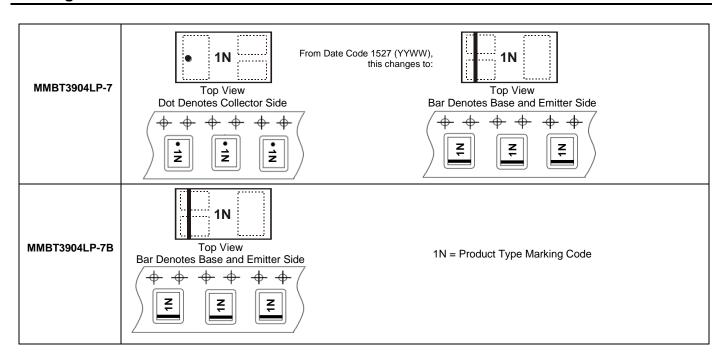
Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
MMBT3904LP-7	1N	7	8mm	3,000
MMBT3904LP-7B	1N	7	8mm	10.000

#### Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



#### **Marking Information**



# **Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	V
Collector Current	Ic	200	mA
Peak Collector Current	Ісм	200	mA

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 5)	400		mW	
Fower Dissipation	(Note 6)	P <sub>D</sub>	1000	IIIVV	
Thermal Resistance, Junction to Ambient	(Note 5)		310	°C/M	
Thermal Resistance, Junction to Ambient	(Note 6)	$R_{ hetaJA}$	120	°C/W	
Thermal Resistance, Junction to Lead	$R_{ heta JL}$	120	°C/W		
Operating and Storage and Temperature Rang	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C		

## ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	В

Notes:

- 5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.
- 6. Same as Note 5, except the exposed collector pad is mounted on 25mm x 25mm 2oz copper.
- 7. Thermal resistance from junction to solder-point (on the exposed collector pad).
- 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



### **Thermal Characteristics**

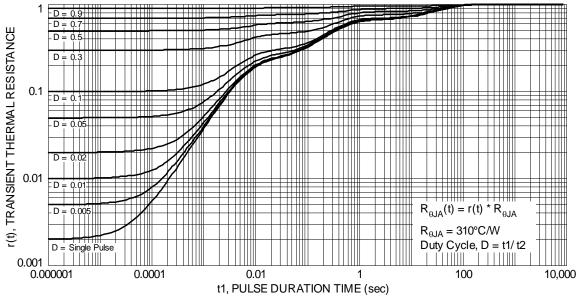
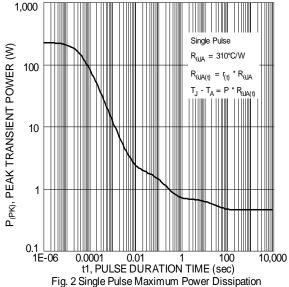


Fig. 1 Transient Thermal Resistance





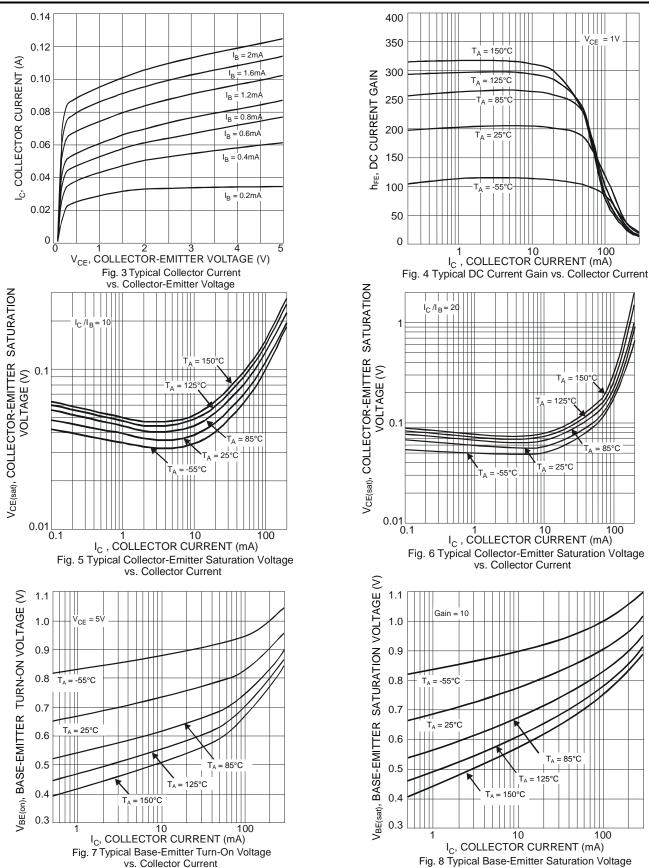
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS					
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	60	_	V	$I_C = 10\mu A, I_E = 0A$
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	40	_	V	$I_C = 1.0 \text{mA}, I_B = 0 \text{A}$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	6.0		V	$I_E = 10\mu A, I_C = 0A$
Collector Cutoff Current	ICEX	_	50	nA	$V_{CE} = 30V$ , $V_{EB(off)} = 3.0V$
Base Cutoff Current	$I_{BL}$	_	50	nA	$V_{CE} = 30V$ , $V_{EB(off)} = 3.0V$
ON CHARACTERISTICS (Note 9)			•		
		40	_		$I_C = 100 \mu A, V_{CE} = 1.0 V$
		70	_		$I_C = 1.0 \text{mA}, V_{CE} = 1.0 \text{V}$
DC Current Gain	hFE	100	300	_	$I_C = 10mA, V_{CE} = 1.0V$
		60	_		I <sub>C</sub> = 50mA, V <sub>CE</sub> = 1.0V
		30	_		I <sub>C</sub> = 100mA, V <sub>CE</sub> = 1.0V
Collector Emitter Saturation Voltage	V	_	0.20	V	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>		0.30		I <sub>C</sub> = 50mA, I <sub>B</sub> = 5.0mA
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	0.65	0.85	V	I <sub>C</sub> = 10mA, I <sub>B</sub> = 1.0mA
Base-Emiller Saturation Voltage			0.95	V	$I_C = 50 \text{mA}, I_B = 5.0 \text{mA}$
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	$C_{obo}$	_	4.0	pF	$V_{CB} = 5.0V$ , $f = 1.0MHz$ , $I_E = 0A$
Input Capacitance	C <sub>ibo</sub>	_	8.5	pF	$V_{EB} = 0.5V$ , $f = 1.0MHz$ , $I_{C} = 0A$
Input Impedance	h <sub>ie</sub>	1.0	10	kΩ	
Voltage Feedback Ratio	h <sub>re</sub>	0.5	8.0	x 10 <sup>-4</sup>	$V_{CE} = 10V, I_{C} = 1.0mA,$
Small Signal Current Gain	h <sub>fe</sub>	100	400	_	f = 1.0kHz
Output Admittance	h <sub>oe</sub>	1.0	40	μs	
Current Gain-Bandwidth Product	f⊤	300	_	MHz	$V_{CE} = 20V, I_{C} = 10mA,$ f = 100MHz
SWITCHING CHARACTERISTICS					
Delay Time	t <sub>d</sub>	_	35	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$
Rise Time	t <sub>r</sub>	_	35	ns	$V_{BE(off)} = 0.5V, I_{B1} = 1.0mA$
Storage Time	t <sub>s</sub>	_	200	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$
Fall Time	t <sub>f</sub>	_	50	ns	$I_{B1} = -I_{B2} = 1.0 \text{mA}$

Note: 9. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.



## Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)



100

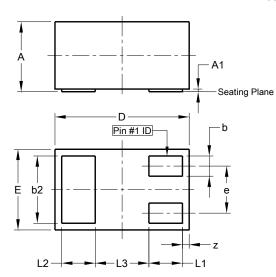
vs. Collector Current



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X1-DFN1006-3

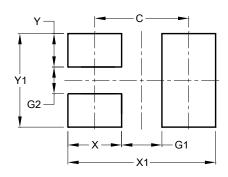


X1-DFN1006-3					
Dim	Min	Max	Тур		
Α	0.47	0.53	0.50		
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	<b>b2</b> 0.45		0.50		
D	0.95	1.075	1.00		
Е	0.55	0.675	0.60		
е	-	-	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3		-	0.40		
z	0.02	0.08	0.05		
All Dimensions in mm					

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X1-DFN1006-3



Dimensions	Value (in mm)		
С	0.70		
G1	0.30		
G2	0.20		
X	0.40		
X1	1.10		
Υ	0.25		
V1	0.70		



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